

(19) United States

(12) Patent Application Publication (10) Pub. No.: US 2024/0179892 A1 JUNG et al.

May 30, 2024 (43) Pub. Date:

(54) SEMICONDUCTOR DEVICE AND METHOD OF FABRICATING THE SAME

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Appl. No.: 18/353,137

Filed: Jul. 17, 2023 (22)

(30)Foreign Application Priority Data

Nov. 29, 2022 (KR) 10-2022-0163399

Publication Classification

(51) Int. Cl. H10B 12/00

(2006.01)

U.S. Cl. (52)

CPC H10B 12/482 (2023.02); H10B 12/02

(2023.02)

(57)ABSTRACT

A semiconductor device may include a substrate including a core region, a cell block region, and a peripheral region, which are sequentially arranged in a first direction, and a bit line structure on the cell block region. The bit line structure may include a first bit line and a second bit line, which extend in the first direction and are adjacent to each other in a second direction crossing the first direction, a bit line connector, which electrically connects the first bit line to the second bit line and is adjacent to the peripheral region, and a bit line pad, which is electrically connected to the first bit line and is adjacent to the core region.



